

ABSTRACT

WIRE STRUCTURE AND WIRE STRUCTURE FORMATION METHOD

5 A wire structure (50A) includes: a column-like bump (45), provided to be adjacent to a
second electronic component (32b) installed on a substrate (31); and a looping wire (50), bonded
onto the substrate (31) to stride over the second electronic component (32b). The looping wire
(50) includes: a second raised part (54), wherein a tip is bonded to the substrate (31) on a side of
the column-like bump (45) opposite to the second electronic component (32b) to be raised from
10 the substrate (31); a loop part (55), extending to stride over the second electronic component
(32b); and a bent part (56), bent to be engaged with an upper end of the column-like bump (45)
to connect the loop part (55) and the second raised part (54).

Figure 3